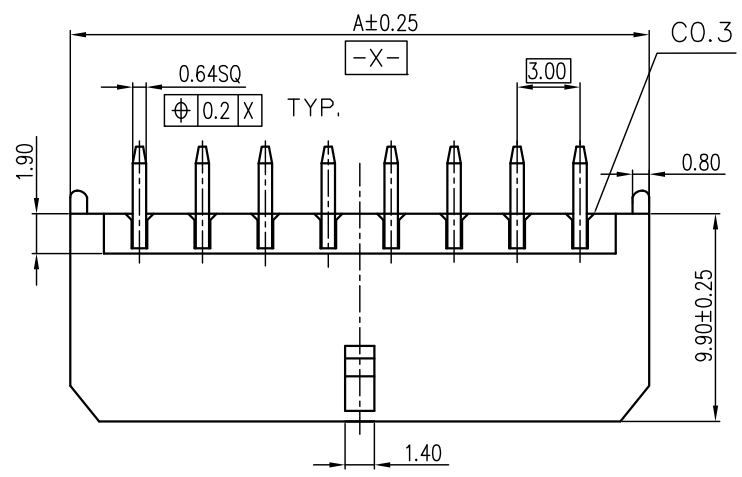


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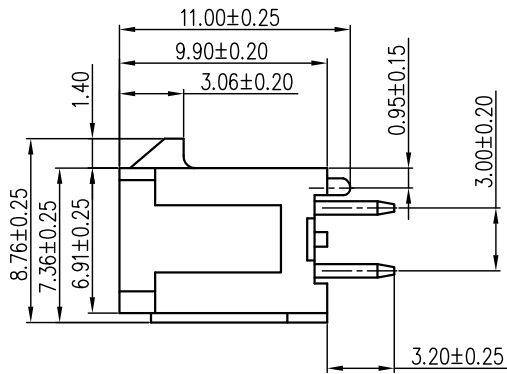
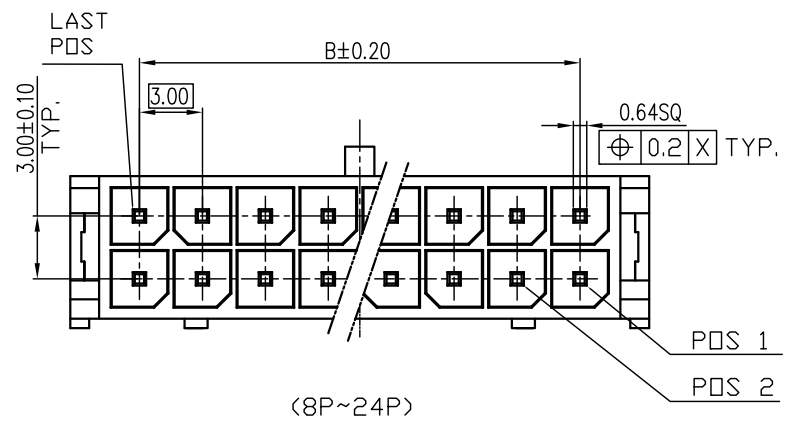
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

**PRELIMINARY RELEASE
SUBJECT TO CHANGE**

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-12149	RELEASE FOR RoHS	08/16/2012	Arron Lin
B	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013	Arron Lin
CX1		UPDATE FOR 2 POS., PACKING QUANTITY AND PLATING	03/03/2014	Arron Lin



- NOTE:
- INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR: BLACK.
 - CONTACT MATERIAL: COPPER ALLOY;
 - FINISH:
CONTACT AREA: SELECTIVE PLATING OPTIONS;
SOLDERING AREA: MATTE TIN PLATING 100 μ" MIN OR GOLD PLATING.;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
 - THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
 - APPLICABLE P.C.BOARD THICKNESS: 1.60mm
 - PACKING MUST BE PER Amphenol PACKING SPECIFICATION



24	39.60	33.00
22	36.60	30.00
20	33.60	27.00
18	30.60	24.00
16	27.60	21.00
14	24.60	18.00
12	21.60	15.00
10	18.60	12.00
08	15.60	9.00
06	12.60	6.00
04	9.60	3.00
02	6.60	NA
NO. OF CIRCUIT	A	B

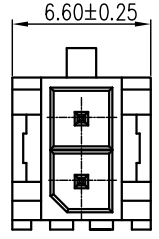
PART NO. G881AXX1X2T3EU
No. OF CIRCUIT

- CONTACT FINISH
- 0: Tin (OVERALL)
 - 1: FLASH GOLD (OVERALL)
 - 2: 15 μ" GOLD
 - 3: 30 μ" GOLD

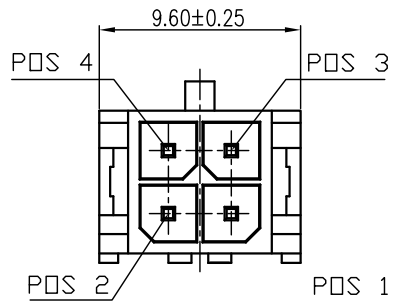
TOLERANCE	APPROVALS	DATE	TITLE		Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation		
X. ±0.30	DRAWN Debby Hung	03/03/2014	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK		UNIT mm	SIZE A3	PART No. G881AXX1X2T3EU
X.X ±0.20	CHECKED Roger Tsai	03/03/2014					
X.XXX ±0.10	APPROVED Arron Lin	03/03/2014					
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD		SCALE NA	SHEET 1 OF 3	DWG No. G881AXX1X2T3EU	REV. CX1
UNLESS OTHERWISE SPECIFIED							

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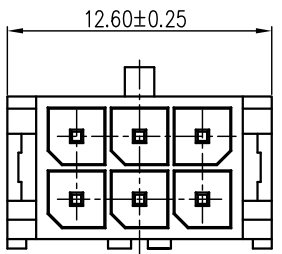
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
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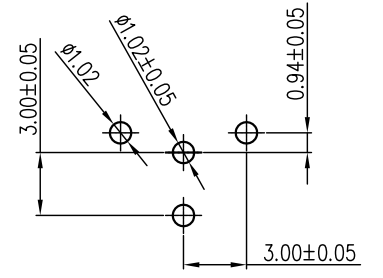
(2X1POS)



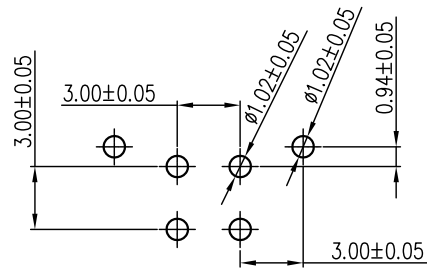
(2X2POS)



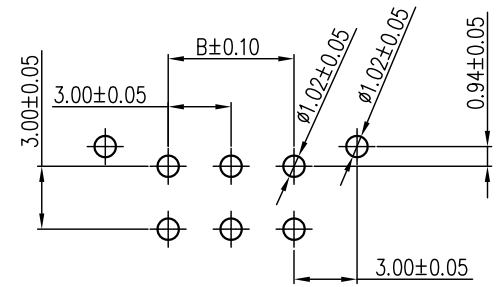
(2X3POS)



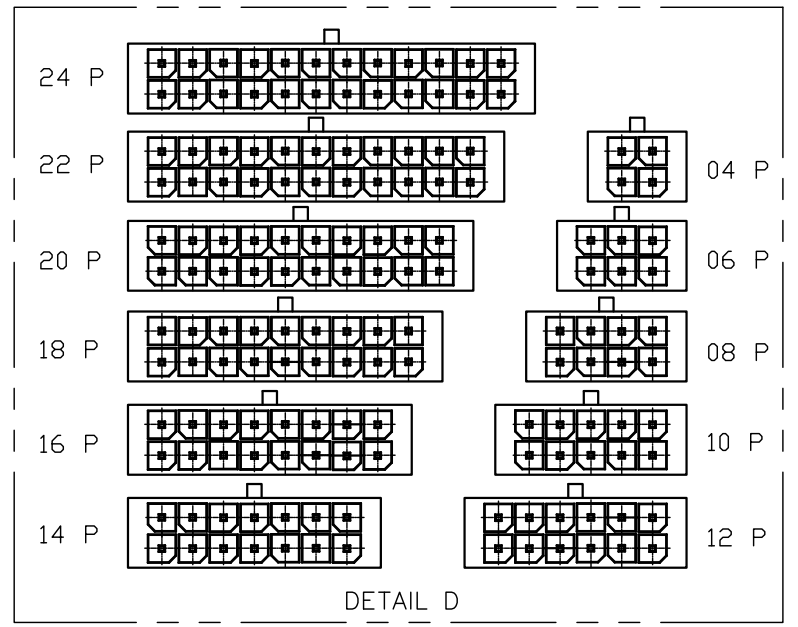
2X1 POSITIONS
RECOMMENDED PCB LAYOUT



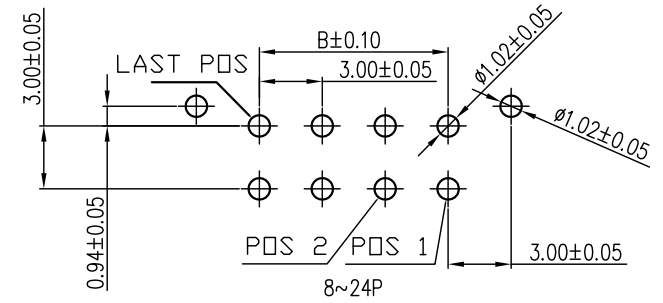
2X2 POSITIONS
RECOMMENDED PCB LAYOUT



2X3 POSITIONS
RECOMMENDED PCB LAYOUT



DETAIL D



8~24P
RECOMMENDED PCB LAYOUT

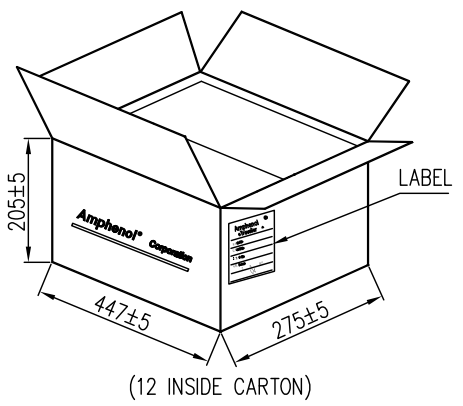
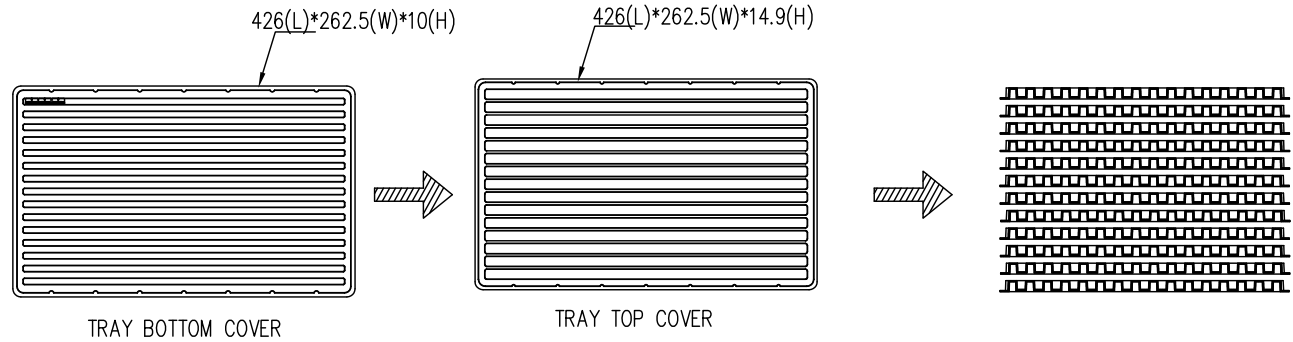
**PRELIMINARY RELEASE
SUBJECT TO CHANGE**

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol [®]				
X.		DRAWN	Debby Hung	03/03/2014	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK		Amphenol Corporation Amphenol Taiwan Corporation				
X.X	±0.30	CHECKED	Roger Tsai	03/03/2014							
X.XX	±0.20	APPROVED	Arron Lin	03/03/2014							
X.XXX	±0.10	DWG TYPE	CUST DWG	PROJECT CODE	PHD	UNIT	mm	SIZE	A3	PART No.	G881AXX1X2T3EU
ANGULAR	±1°					SCALE	NA	SHEET	2 OF 3	DWG No.	G881AXX1X2T3EU
UNLESS OTHERWISE SPECIFIED										REV.	CX1

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PRELIMINARY RELEASE
SUBJECT TO CHANGE



POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

NOTE:
 1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 3. THICKNESS : 0.80±0.05mm.

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation							
X.		DRAWN	Debby Hung	03/03/2014	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK		UNIT	mm	SIZE	A3	PART No.	G881AXX1X2T3EU		
X.X	±0.30	CHECKED	Roger Tsai	03/03/2014			SCALE	NA	SHEET	3 OF 3	DWG No.	G881AXX1X2T3EU	REV.	CX1
X.XX	±0.20	APPROVED	Arron Lin	03/03/2014			UNLESS OTHERWISE SPECIFIED		DWG TYPE		CUST DWG	PROJECT CODE		PHD
X.XXX	±0.10													
ANGULAR	±1°													